SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688, SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

SDLS008

D2617, JANUARY 1981 - REVISED MARCH 1988

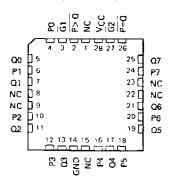
- Compares Two-8-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- Hysteresis at P and Q Inputs
- 'LS682 has 20-kΩ Pullup Resistors on the Q Inputs
- SN74LS686 and 'LS687 . . . JT and NT 24-Pin, 300-Mil Packages

TYPE	P = Q	P > 0	OUTPUT	OUTPUT	20-kΩ
	F = U	rzu	ENABLE	CONFIGURATION	PULLUP
'LS682	yes	yes	no	totem-pole	yes
'L\$684	yes	yes	no	totem-pole	no
'LS685	γ е 5	γes	na	open-collector	no
SN74LS686	yes	ves	yes	totem-pole	no
'LS687	yes	yes	yes	open-collector	no
'LS688	yes	no	yes	totem-pole	no

SN54LS687 . . . JT PACKAGE SN74LS686, SN74LS687 . . . DW OR NT PACKAGE (TOP VIEW)

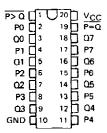
> P>Q | 1 | 24 | VCC G1 | 2 | 23 | G2 P0 | 3 | 22 | P=Q O0 | 4 | 21 | Q7 P1 | 5 | 20 | P7 Q1 | 6 | 19 | NC NC | 7 | 18 | Q6 P2 | 8 | 17 | P6 Q2 | 9 | 16 | Q5 P3 | 10 | 15 | P5 Q3 | 11 | 14 | Q4 GND | 12 | 13 | P4

\$N54L\$687 . . . FK PACKAGE (TOP VIEW)

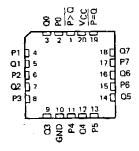


NC-No internal connection

\$N54L\$682, \$N54L\$684, \$N54L\$685 . . . J PACKAGE \$N74L\$682, \$N74L\$684, \$N74L\$685 . . . DW OR N PACKAGE (TOP VIEW)

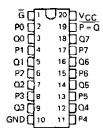


SN54LS682, SN54LS684, SN54LS685 . . . FK PACKAGE (TOP VIEW)

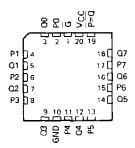


SN54LS688 . . . J PACKAGE SN74LS688 . . . DW OR N PACKAGE

(TOP VIEW)



SN54LS688 . . . FK PACKAGE (TOP VIEW)



SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688 SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

description

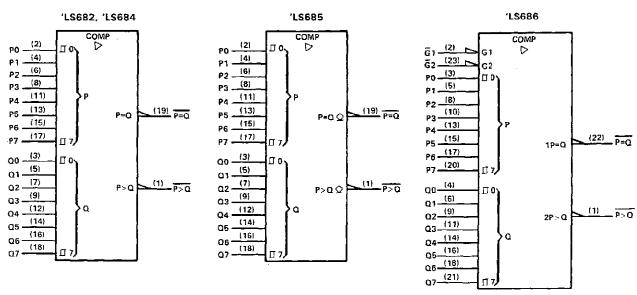
These magnitude comparators perform comparisons of two eight-bit binary or BCD words. All types provide $\overline{P}=\overline{Q}$ outputs and all except 'LS688 provide $\overline{P}>\overline{Q}$ outputs as well. The 'LS682, 'LS684, 'LS685, and 'LS688 have totem-pole outputs, while the 'LS685 and 'LS687 have open-collector outputs. The 'LS682 features 20-k Ω pullup termination resistors on the Q inputs for analog or switch data.

FUNCTION TABLE

	INPUTS		OUTI	PUTS
DATA	ENAB	ES	P=Q	P>Q
P, Q	Ğ, <u>G1</u>	G2		.,,,
P=Q	L	Х	L	н
P>Q	×	Ļ	н	L
P <q< td=""><td>X</td><td>X</td><td>н</td><td>Н_</td></q<>	X	X	н	Н_
P = Q	Н	X	Н	Н
P>Q	×	Н] н	Н
×	Н] н	Н	н

- NOTES: 1. The last three lines of the function table applies only to the devices having enable inputs, i.e., 'LS686 thru 'LS688.
 - 2. The $\overline{P < Q}$ function can be generated by applying the $\overline{P Q}$ and $\overline{P > Q}$ outputs to a 2-input NAND gate.
 - 3. For 'LS686 and 'LS687, \overline{G} 1 enables $\overline{P} = \overline{Q}$ and \overline{G} 2 enables $\overline{P} > \overline{Q}$.

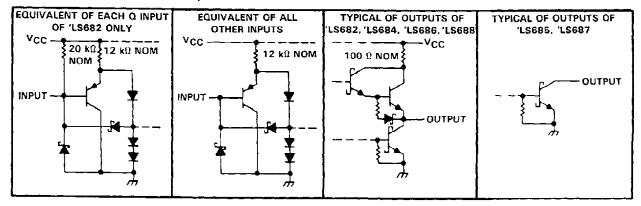
logic symbols†



 † These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

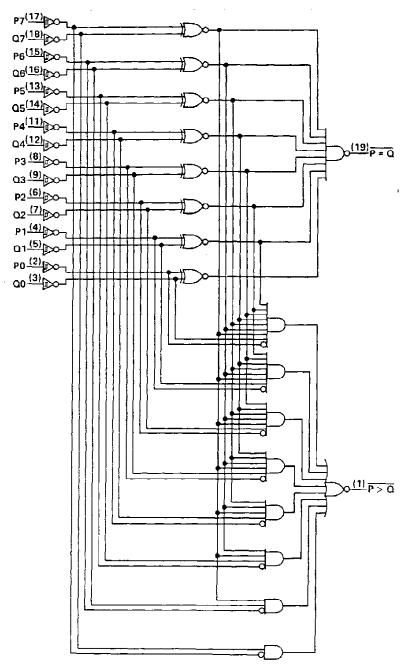
logic symbols† (continued) 'LS687 'LS688 COMP COMP 12) ãi. P0 (2) G1 Ğ2 (23) ► G2 ە □ (3) P1 (4) PO. ים דו (5) (6) P2 -(8) P3 (B) P2 -P4 (11) (10) P3 (13) (13) P5 -1151 (22) P=0 (15) P5 -1₽=0 ☆ P6 -P6 [17] P7 (17) (19) P=Q رد 🛚 P7 (20) 1P=Q ք 7 00 (3) [] 0_] (4) 01 (5) Q0-Πο, Q1 (6) Q2 (7) Q2 (9) Q3 (9) (1) 03 (11) 2P -Q Q 04 (12) ò (14) Q Q5 (16) Q4-Q5 (16) Q6• 06 (18) 07 (18) 07- (21)

schematics of inputs and outputs



[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

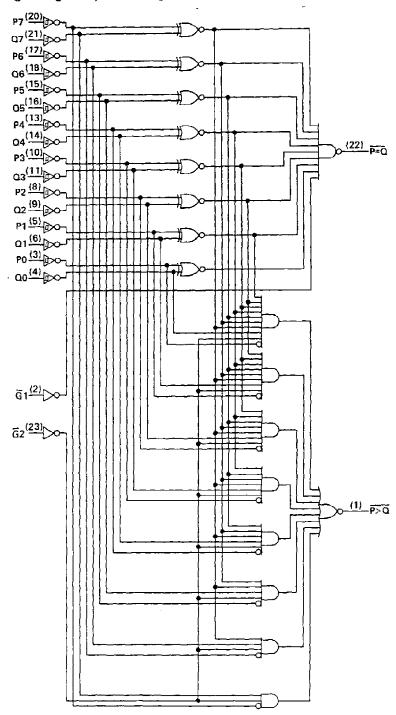
'LS682, 'LS684, 'LS685 logic diagram (positive logic)



Pin numbers shown are for DW, J, and N packages.



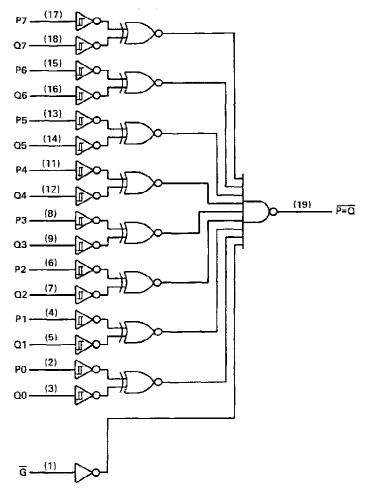
'LS686, 'LS687 logic diagram (positive logic)



Pin numbers shown are for DW, JT, and NT packages.



'LS688 logic diagram (positive logic)



Pin numbers shown are for DW, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: Q inputs of 'LS682	, 5 .5 V
All other inputs	
Off-state output voltage: 'LS685, 'LS687	
Operating free-air temperature range:	
SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688	-55°C to 125°C
SN74LS682, SN74LS684 thru SN74LS688	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN54LS682, SN54LS684, SN54LS688 SN74LS682, SN74LS684, SN74LS686, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

recommended operating conditions

		SN54LS'				SN74LS'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, VCC	4.5	5	5.5	4.85	5	5.25	>	
High-level output current, IOH			-400			-400	μΑ	
Low-level output current, IOI			12			24	mΑ	
Operating free-air temperature, TA	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		_				SN54LS	3'	S	N74LS	•	
	PARAMETE	R	TEST CO	VDITIONS [†]	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
V _{IH}	High-level inpu	ut voltage			2			2			V
VIL	Low-level inpu	ut voltage					0.7			0.8	V
	. Hysteresis	P or Q inputs	V _{CC} = MIN			0.4			0.4		٧
VIK	Input clamp v	oltage	VCC = MIN.	ij = -18 mA			-1.5			- 1.5	>
Voн	High-level out	put voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	$V_{1H} = 2 V$, $I_{OH} = -400 \mu A$	2.5			2.7			>
VOL	Low-level out	out voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	IOL = 12 mA		0.25	0.4		0.25	0.4	٧
VOL Low-level output voltage		pat voltage	V _{IL} = V _{IL} max	iOL = 24 mA					0.35	0.5	
h	Input current at maximum	Q inputs, 'LS682	VCC = MAX,	V ₁ = 5.5 V			0.1			0.1	mA
'I 		All other inputs	V _{CC} = MAX,	V ₁ = 7 V			0.1				,,,,,
ΊΗ	High-level inp	ut current	V _{CC} = MAX,	V ₁ = 2.7 V			20			20	μA
կլ		Q inputs, 'LS682' All other inputs	V _{CC} = MAX,	V _I = 0.4 V			-0.4 -0.2			-0.4 -0.2	mA
los§	Short-circuit o	output current	VCC = MAX.	Vo = 0	- 20		- 100	- 20		- 100	mA
		'LS682				42	70		42	70	
loc.	Supply curren	'LS684	Voc - MAY	See Note 1		40	65		40	65	mA
CC	Supply current	'LS686	VCC = MAX, Se	SEE MOTE 1		44	75		44	75	5]
		'LS688			40	65		40	65		

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 1: ICC is measured with any G inputs grounded, all other inputs at 4.5 V, and all outputs open.

SN54LS682, SN54LS684, SN54LS688 SN74LS682, SN74LS684, SN74LS686, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER†	FROM	TO	TEST	'LS68	2	'LS68	4	'LS68	6	'LS68	8	UNIT			
LANAMETER.	(INPUTS)	(OUTPUT)	CONDITIONS	MIN TYP	MAX	MIN TYP	MAX	MIN TYP	MAX	MIN TYP	MAX	UNIT			
t _{PLH}	P	P≖Q	•	13	25	15	25	13	25	12	18				
t _{PHL}		1				15	25	17	25	20	30	17	23	ns	
^t PLH	α	$\overline{P} = \overline{Q}$		14	25	16	25	13	25	12	18				
tPHL_	<u> </u>	r = Q	R _I = 667 Ω,	15	25	15	25	21	30	17	23	ns			
tPLH.	G, G1	P=O	· ·					11	20	12	18	ns			
^t PHL	G, G1		CL = 45 pF, All other inputs low,	_					19	30	13	20	i ns		
tPLH	Р	P>Q		20	30	22	30	19	30						
tPHL	<u>-</u>	FZU			· ·	1	See Note 2	15	30	17	30	15	30		
†PLH	0	P>0	See Note 2	21	30	24	30	18	30						
tPHL	u	טכה		19	30	20	30	19	30			ns			
^t PLH	Ğ2	<u> </u>				<u>-</u>		21	30						
tpHI	<u> </u>	Ğ2 P>Q						16	25			ns			

 $^{^{\}dagger}$ tpLH = propagation delay time, low-to-high-level outputs; tpHL = propagation delay time, high-to-low-level output. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN54LS685, SN54LS687 SN74LS685, SN74LS687, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

recommended operating conditions

		SN54LS'			SN74LS'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.85	5	5.25	V
High-level output current, VOH			5.5			5.5	V
Low-level output current, IQL			12			24	mA
Operating free-air temperature, TA	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DARAMETER		uziono!	5	N54L	3'	s	N74LS	•	UNIT
	PARAMETER	TEST CONE	MIN	TYP	MAX	MIN	TYP	MAX	ONIT	
VIH	High-level input voltage			2			2			٧
VIL	Low-level input voltage					0.7			8.0	V
V _{T+} - '	V _T _ Hysteresis P or Q inputs	VCC = MIN			0.4			0.4		٧
V_{iK}	Input clamp voltage	VCC = MIN,	I _I = -18 mA			- 1.5			-1.5	٧
Іон	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, V _{OH} = 5.5 V			250			100	μА
Vol	Low-level output voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	v
- OL	as in love surput valuage	VIL = VILmax	l _{OL} = 24 mA					0.35	0.5	1
Iq		VCC = MAX,	V ₁ = 7 V			0.1			0.1	mA
_'IH	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V			20			20	μΑ
IIL	Low-level input current	V _{CC} ≈ MAX,	V ₁ = 0.4 V			-0.2			-0.2	mA
	Supply 'LS685		Con Nove 1		40	65		40	65	A
lcc	current 'LS687	$V_{CC} = MAX,$	See Note 1		44	75		44	75	mA

 $^{^{\}dagger}$ For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. NOTE 1: I_{CC} is measure with any \overline{G} inputs grounded, all other inputs at 4.5 V, and all outputs open.

SN54LS685, SN54LS687 SN74LS685, SN74LS687 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH OPEN-COLLECTOR OUTPUTS

switching characteristics, VCC = 5 V, TA = 25 °C

PARAMETER	FROM	то	7507 00101710110		'LS685			'LS687		UNIT				
PARAIVIETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONT				
tPLH .	P	P=Q			30	45		24	35					
†PHL	F)			19	35		20	30	ns				
tPLH.	Q	P≂Œ			24	45		24	35					
^t PHL	<u>u</u>	P=U	D 867.0		23	35		20	30	ns				
tPLH	ਰ, ਰ 1	P=Q	$R_{L} \simeq 667 \Omega$					21	35					
TPHL	G, G1	P=Q	Cլ = 45 pF,					18	30	ns				
t _{PLH}	Р		All other		32	45		24	35					
[†] PHL	P	P>Q P>Q	 	P>Q	P>Q	P>Q	inputs low,		16	35		16	30	ns
t _{PLH}	a			See Note 2		30	45		24	35				
tPHL	u			P>Q	P>Q	{ P>Q	P>Q	P>Q			20	35		16
tPLH	<u>G</u> 2	B C						24	35					
[†] PHL	G2	P>0	· a					15	30	ns				

 $^{^{\}dagger}$ tpLH = propagation delay time, low-to-high-level outputs; tpHL = propagation delay time, high-to-low-level output. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
8415101RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101RA SNJ54LS682J	Samples
8415101SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
8415101SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
84152012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84152012A SNJ54LS 684FK	Samples
8415201RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415201RA SNJ54LS684J	Samples
84153012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84153012A SNJ54LS 688FK	Samples
8415301RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415301RA SNJ54LS688J	Samples
8415301SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415301SA SNJ54LS688W	Samples
SN54LS682J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS682J	Samples
SN54LS682J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS682J	Samples
SN54LS684J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS684J	Samples
SN54LS688J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS688J	Samples
SN74LS682DW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	
SN74LS682DW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples
SN74LS682N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS682N	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN74LS682N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS682N	Samples
SN74LS682NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS682	Samples
SN74LS682NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS682	Samples
SN74LS684DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS684	Samples
SN74LS684N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS684N	Samples
SN74LS684NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS684	Samples
SN74LS688DW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS688	
SN74LS688DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS688	Samples
SN74LS688N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS688N	Samples
SN74LS688NE4	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS688N	Samples
SN74LS688NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS688	Samples
SNJ54LS682J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101RA SNJ54LS682J	Samples
SNJ54LS682J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101RA SNJ54LS682J	Samples
SNJ54LS682W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
SNJ54LS682W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
SNJ54LS684FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84152012A SNJ54LS 684FK	Samples
SNJ54LS684J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415201RA SNJ54LS684J	Samples
SNJ54LS688FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84153012A SNJ54LS 688FK	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS688J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415301RA SNJ54LS688J	Samples
SNJ54LS688W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415301SA SNJ54LS688W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54LS682, SN54LS684, SN54LS688, SN74LS682, SN74LS684, SN74LS688:

• Catalog : SN74LS682, SN74LS684, SN74LS688

• Military: SN54LS682, SN54LS684, SN54LS688

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS682DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS682NSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LS684DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS684NSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LS688DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS688NSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS682DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS682NSR	so	NS	20	2000	367.0	367.0	45.0
SN74LS684DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS684NSR	so	NS	20	2000	367.0	367.0	45.0
SN74LS688DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS688NSR	so	NS	20	2000	367.0	367.0	45.0

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
8415101SA	W	CFP	20	25	506.98	26.16	6220	NA
84152012A	FK	LCCC	20	55	506.98	12.06	2030	NA
84153012A	FK	LCCC	20	55	506.98	12.06	2030	NA
8415301SA	W	CFP	20	25	506.98	26.16	6220	NA
SN74LS682DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LS682N	N	PDIP	20	20	506	13.97	11230	4.32
SN74LS684N	N	PDIP	20	20	506	13.97	11230	4.32
SN74LS688DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LS688N	N	PDIP	20	20	506	13.97	11230	4.32
SN74LS688NE4	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54LS682W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54LS684FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS688FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS688W	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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